CLAIMS

1. A film comprising a substrate, a base layer, and an adhesive layer in this order,

wherein the base layer comprises a reaction cured product of a (meth)acrylic polymer and a curing agent,

the base layer has a thickness of 0.1 μm to 3.0 μm, and

the base layer has an elongation rate of 90% or more as measured by a tensile test at 25°C and a speed of 100 mm/min and determined by the following formula,

Elongation rate (%) = (elongation (mm) at break) × 100/(distance (mm) between grippers before applying tension).

2. A film comprising a substrate, a base layer, and an adhesive layer in this order,

wherein the base layer has a thickness of 0.1 μm to 3.0 μm, and

the base layer comprises a reaction cured product of a (meth)acrylic polymer and a curing agent which is at least one selected from the group consisting of a metal chelate and an epoxy compound, and

the (meth)acrylic polymer comprises a carboxy group-containing (meth)acrylic polymer.

3. The film according to claim 2, wherein the base layer has an elongation rate of 90% or more as measured by a tensile test at 25°C and a speed of 100 mm/min and determined by the following formula,

Elongation rate (%) = (elongation (mm) at break) × 100/(distance (mm) between grippers before applying tension).

4. The film according to any one of claims 1 to 3, wherein the base layer has an acid value of 1 mgKOH/g to 80 mgKOH/g.

5. The film according to any one of claims 1 to 4, wherein the curing agent comprises a metal chelate, and an amount of the metal chelate is 0.1 parts by mass to 10 parts by mass with respect to 100 parts by mass of the (meth)acrylic polymer.

6. The film according to any one of claims 1 to 5, wherein the curing agent comprises an epoxy compound, and an amount of the epoxy compound is 0.1 parts by mass to 10 parts by mass with respect to 100 parts by mass of the (meth)acrylic polymer.

7. The film according to any one of claims 1 to 6, wherein the substrate comprises a fluorine resin.

8. The film according to claim 7, wherein the fluorine resin comprises at least one selected from the group consisting of an ethylene-tetrafluoroethylene copolymer, a tetrafluoroethylene-hexafluoropropylene copolymer, a tetrafluoroethylene-perfluoro(alkyl vinyl ether) copolymer, and a tetrafluoroethylene-hexafluoropropylene-vinylidene fluoride copolymer.

9. The film according to any one of claims 1 to 8, wherein the substrate is subjected to a corona treatment or a plasma treatment.

10. The film according to any one of claims 1 to 9, wherein the adhesive layer comprises a reaction cured product of a hydroxy group-containing (meth)acrylic polymer and a polyfunctional isocyanate compound.

11. The film according to any one of claims 1 to 10, further comprising an antistatic layer between the base layer and the adhesive layer.

12. The film according to any one of claims 1 to 11, being a mold release film used in a process of encapsulating a semiconductor device with a curable resin.

13. A method for manufacturing a semiconductor package, the method comprising:

placing the film according to any one of claims 1 to 12 in an inner surface of a mold;

placing a substrate to which a semiconductor device is fixed in the mold in which the film is placed;

encapsulating the semiconductor device in the mold with a curable resin to prepare

an encapsulated body; and

releasing the encapsulated body from the mold.